

ABSTRACT OF THE INVENTION

A silicon wafer has a B-stageable underfill material deposited on the active face of the wafer. The B-stageable underfill comprises a first composition with a lower curing temperature and a second composition with a higher curing temperature, characterized in that the first composition has been fully cured.

1. A silicon wafer having a B-stageable underfill material deposited on the active face of the wafer, the B-stageable underfill comprising a first composition with a lower curing temperature and a second composition with a higher curing temperature, characterized in that the first composition has been fully cured.